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Strategic Direction and Financial Targets

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Agenda



- Recent Steps
- Current Status
- Driving Growth
- Driving Margins
- Reducing Capital Intensity
- Summary

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Recent Steps



Strategic Redirection

3 to

Recent Steps



Automotive, Industrial & Multimarket

- Turn-around Discretes
- Turn-around Chipcard
- Ramp-up of new power fab in Kulim, Malaysia, in record time

Recent Steps



Communication Solutions

- Profit, Share Gains in Access
- Turn-around in Tuner, RF Power
- Customer Wins in Baseband: Nokia, LG, Panasonic and others

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Revenue

> € 4 billion



More than

30,000 employees



R&D Spending

~ € 800 m

Some 6,000 R&D staff



More than

20,000

patents



Power



Source: IMS Research, Sep. 2006



Wireline Access



Source: Gartner Dataquest, June 2006



Wireless TRx



Source: Gartner Dataquest, Strategy Analytics, Infineon



Chipcard

Market Share 29%



Source: Gartner Dataquest, June 2006



Automotive



Source: Strategy Analytics, May 2006

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Energy Efficiency

- Energy savings in power generation
- Energy savings in power transmission
- Energy savings in power consumption



Security

- Protection and privacy of personal and company data
- Secure e-commerce
- Contactless identification and payment



Connectivity

- Mobile Phone Platforms: full suite of solutions
- Broadband Access: CO and CPE
- Leader in RF: wireless connectivity everywhere



Growth in Auto

- Growth Drivers Body and Safety
- Hybrid Cars
- Automotive Connectivity



Growth in Industry

- CoolMOS in AC/DC
- OptiMOS in DC/DC
- IGBTs in DC/AC



Growth in Broadband

- VINAX for VDSL2
- Danube for ADSL2 / VolP
- CPE



Growth in Wireless

- Design Win Momentum in Single Chip Phones
- Design Win Momentum in Platforms
- Design Win Momentum in RF CMOS Transceivers

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In FY 2006

Double-digit EBIT margin

on

~ € 3 bn in sales



In FY 2006

EBIT loss on ~ € 1 bn sales

in

Chipcard and mainly Baseband



AIM in FY 2006 Expense > € 70 m for Fabs

Zero from Sep. 2007 on



Chipcard in FY 2006 Double-digit € m loss

Chipcard in FY 2007

Break-Even and New Products



Baseband in FY 2006 Causing Losses in COM

Baseband in FY 2007+

Design Wins & Strong Ramp



Target: ~ 10% EBIT Margin

FY 2007: ~ EBIT Break-Even

FY 2009: ~ 10% EBIT Margin

FY 2008: well on our way towards 10%

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Reducing Capital Intensity



Advanced Logic

65 nm fabless

Specialty Technologies

In-house

Reducing Capital Intensity



CapEx / Sales

10-12%

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FY 2007

- Ramp Baseband
- Stabilize Chipcard
- Lower Fab Expenses
- Break-Even EBIT

Summary



FY 2008 and Beyond

- Sales growth in AIM and COM
- 10+% EBIT margin in AIM, profit in COM
- ~ 10% EBIT margin FY2009, well on our way towards that in FY 2008
- Lower capital intensity

Infineon – Never stop thinking

